

Surface Preparation and Cleaning Conference 2016 (SPCC 2016)

Santa Clara, California, USA
19 - 20 April 2016

ISBN: 978-1-5108-2572-7

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Red Hook, NY 12571



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Surface Preparation and Cleaning Conference (SPCC)
c/o Mark Thirsk
Linx Consulting-PO Box 384
Mendon, MA 01756-0384
USA

Phone: 617-273-8837

mthirsk@linx-consulting.com

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